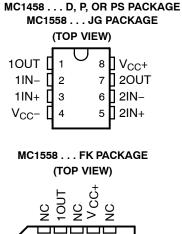
SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

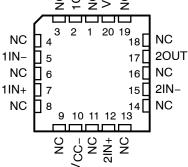
- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

description/ordering information

The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the μ A741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.





NC - No internal connection

ORDERING INFORMATION

T _A	V _{IO} max AT 25°C	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
		PDIP (P)	Tube	MC1458P	MC1458P		
	6 mV		Tube	MC1458D	M04450		
0°C to 70°C		SOIC (D)	Tape and reel	MC1458DR	MC1458		
		SOP (PS)	Tape and reel	MC1458PSR	M1458		
		CDIP (JG)	Tube	MC1558JG	MC1558JG		
–55°C to 125°C	°C 5 mV	CDIP (JGB)	Tube	MC1558JGB	MC1558JGB		
		LCCC (FK)	Tube	MC1558FK	MC1558FK		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

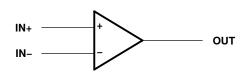
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



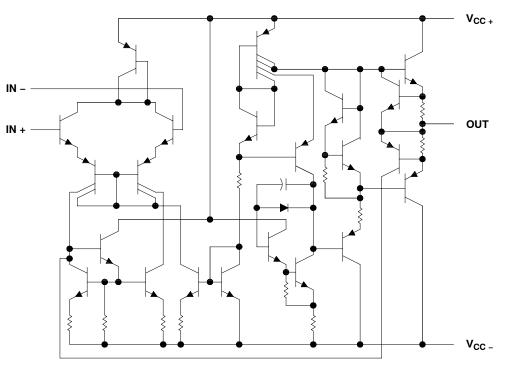
 $Copyright © 2002, \ Texas \ Instruments \ Incorporated \\ On products \ compliant to \ MIL-PRF-3853, all parameters are tested \\ unless \ otherwise \ noted. \ On all \ other \ products, \ products,$

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symbol (each amplifier)



schematic (each amplifier)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC+} (see Note 1):	MC1459		10 \/
Supply vollage, vCC+ (see Note 1).			
	MC1558		
Supply voltage, V _{CC} (see Note 1):	MC1458		18 V
	MC1558		22 V
Differential input voltage, VID (see No	ote 2)		±30 V
Input voltage, VI (either input, see No			
Duration of output short circuit (see I			
Operating virtual junction temperatur	-		
Package thermal impedance, θ_{JA} (see	-		
	,	P package	85°C/W
		PS package	
Package thermal impedance, θ_{JC} (see	ee Notes 7 and 8):		
	,	JG package	14.5°C/W
Case temperature for 60 seconds: F			
Lead temperature 1,6 mm (1/16 inch) from case for 10	seconds: JG package	300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 :	seconds: D, P, or PS package	260°C
Storage temperature range, T _{stg}	·		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 - 2. Differential voltages are at IN+ with respect to IN -.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
$V_{CC\pm}$	Supply voltage		±5	±15	V
-		MC1458	0	70	°C
IA	Operating free-air temperature range	-55	125	°C	



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electrical characteristics at specified free-air temperature, V_{CC\pm} = ± 15 V

			MC1458			MC1558					
	PARAMETER	TES	MIN	ТҮР	MAX	MIN	TYP	MAX	UNIT		
.,				25°C		1	6		1	5	
V _{IO}	Input offset voltage	V _O = 0		Full range			7.5			6	mV
				25°C		20	200		20	200	
I _{IO}	Input offset current	V _O = 0		Full range			300			500	nA
				25°C		80	500		80	500	
I _{IB}	Input bias current	V _O = 0		Full range			800			1500	nA
	Common-mode input			25°C	±12	±13		±12	±13		
V _{ICR}	voltage range			Full range	±12			±12			V
		$R_L = 10 \ k\Omega$		25°C	±12	±14		±12	±14		
.,	Maximum peak output	$R_L \ge 10 \ k\Omega$		Full range	±12			±11			.,
V _{OM}	voltage swing	$R_L = 2 k\Omega$		25°C	±10	±13		±10	±13		V
		$R_L \ge 2 k\Omega$		Full range	±10			±10			
	Large-signal differential			25°C	20	200		50	200		V/mV
A _{VD}	voltage amplification	$R_L \ge 2 k\Omega$,	V _O = ±10 V	Full range	15			25			
B _{OM}	Maximum-output-swing bandwidth (closed loop)	$\begin{array}{l} R_{L} = 2 \; k \Omega, \\ A_{VD} \; = 1, \end{array}$	$V_O \ge \pm 10 V$, THD $\ge 5\%$	25°C		14			14		kHz
B ₁	Unity-gain bandwidth			25°C		1			1		MHz
φm	Phase margin	A _{VD} = 1		25°C		65			65		deg
	Gain margin			25°C		11			11		dB
r _i	Input resistance			25°C	0.3	2		0.3*	2		MΩ
r _o	Output resistance	V _O = 0,	See Note 9	25°C		75			75		Ω
Ci	Input capacitance			25°C		1.4			1.4		pF
z _{ic}	Common-mode input impedance	f = 20 Hz		25°C		200			200		MΩ
01455	Common-mode	V _{IC} = V _{ICR} m	iin,	25°C	70	90		70	90		9
CMRR	rejection ratio	$V_0 = 0$		Full range	70			70			dB
	Supply-voltage	V _{CC} = ±9 V t	o +15 V	25°C		30	150		30	150	
k _{SVS}	sensitivity (ΔV _{IO} /ΔV _{CC})	$V_{O} = 0$	0 ± 10 v ,	Full range			150			150	μV/V
Vn	Equivalent input noise voltage (closed loop)	A _{VD} = 100, f = 1 kHz,	R _S = 0, BW = 1 Hz	25°C		45			45		nV/√H
I _{OS}	Short-circuit output current			25°C		±25	±40		±25	±40	mA
	Supply current		1	25°C		3.4	5.6		3.4	5	
Icc	(both amplifiers)	V _O = 0, No	load	Full range			6.6			6.6	mA
D	Total power dissipation		l	25°C		100	170		100	150	
P _D	(both amplifiers)	V _O = 0, No	load	Full range			200			200	mW
V ₀₁ /V ₀₂	Crosstalk attenuation			25°C		120			120		dB

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

[†] All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is – 55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.



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					MC1458		Γ					
	PARAMETER	TEST COL	TEST CONDITIONS			MAX	MIN	TYP	MAX	UNIT		
	Rise time	V _I = 20 mV,	$R_L = 2 k\Omega$,		0.3			0.3		μs		
t _r	Overshoot factor	V _I = 20 mV,	$R_L = 2 k\Omega$		5			5		%		
SR	Slew rate at unity gain	V _I = 10 V,	$R_L = 2 \ k\Omega$		0.5			0.5		V/µs		

operating characteristics, $V_{CC\pm} = \pm 15$ V, $C_L = 100$ pF, $T_A = 25^{\circ}C$ (see Figure 1)

PARAMETER MEASUREMENT INFORMATION

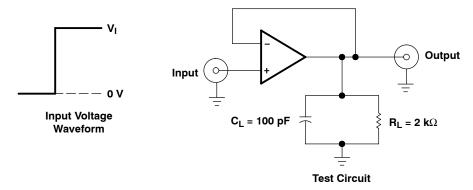


Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit





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31-Jul-2010

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9760301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9760301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1458D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
MC1458PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
MC1458PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1458PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1458PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1558FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
MC1558JG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1558JGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1558P	OBSOLETE	E PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Available
SN98212P	OBSOLETE	E PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows: ACTIVE: Product device recommended for new designs. LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



www.ti.com

31-Jul-2010

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and package die adhesive used between the die adhesive used between the die adhesive used between the die adhesive used betw

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF MC1558, MC1558M :

Catalog: MC1558

• Military: MC1558M

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

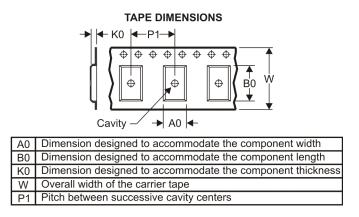
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

28-Feb-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC1458DR	SOIC	D	8	2500	340.5	338.1	20.6
MC1458DR	SOIC	D	8	2500	346.0	346.0	29.0
MC1458PSR	SO	PS	8	2000	346.0	346.0	33.0

MECHANICAL DATA

MCER001A - JANUARY 1995 - REVISED JANUARY 1997



CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE

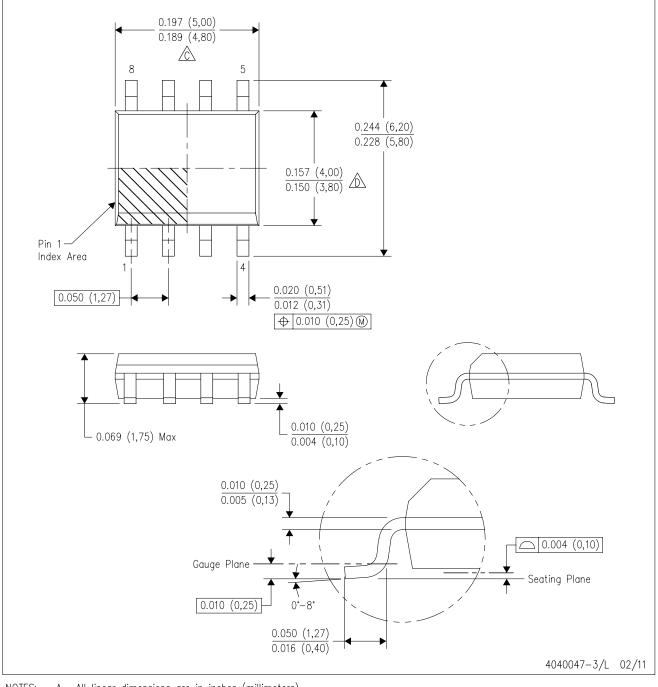


- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

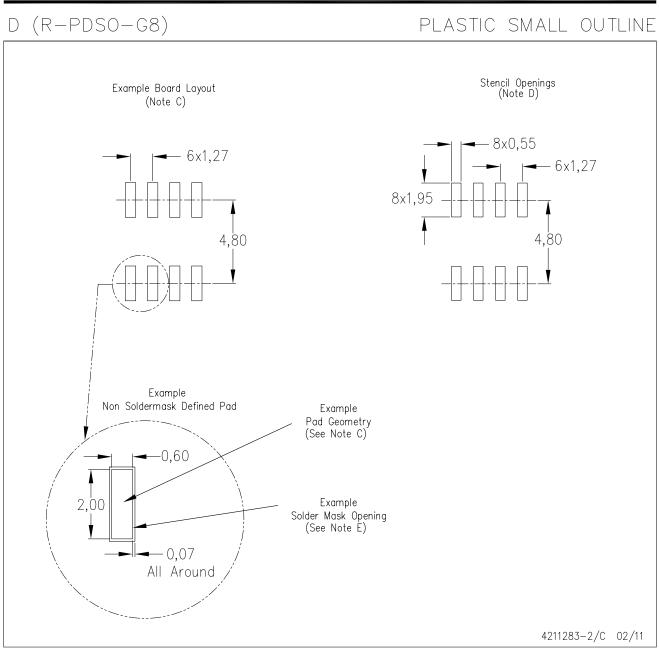


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



LAND PATTERN DATA



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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